

# LN2162C68TR

## Surface Mounting Chip LED

GW Bi-Color Type

### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

- Pure Green

Parameter	Symbol	Rating	Unit
Power dissipation	$P_D$	45	mW
Forward current	$I_F$	15	mA
Pulse forward current *	$I_{FP}$	60	mA
Reverse voltage	$V_R$	3	V
Operating ambient temperature	$T_{opr}$	-25 to +80	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-30 to +85	$^\circ\text{C}$

Note) \*: The condition of  $I_{FP}$  is duty 10%, Pulse width 1 msec.

### ■ Lighting Color / Lens Color

- Pure Green / Clear
- Orange / Clear

- Orange

Parameter	Symbol	Rating	Unit
Power dissipation	$P_D$	45	mW
Forward current	$I_F$	15	mA
Pulse forward current *	$I_{FP}$	60	mA
Reverse voltage	$V_R$	3	V
Operating ambient temperature	$T_{opr}$	-25 to +80	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-30 to +85	$^\circ\text{C}$

Note) \*: The condition of  $I_{FP}$  is duty 10%, Pulse width 1 msec.

### ■ Electro-Optical Characteristics $T_a = 25^\circ\text{C}$

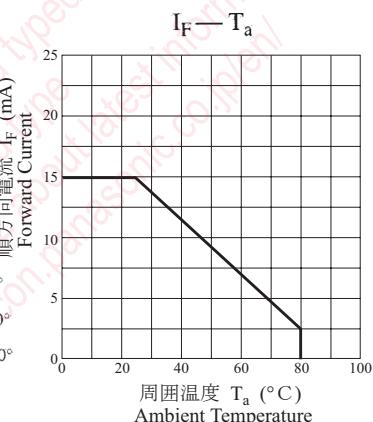
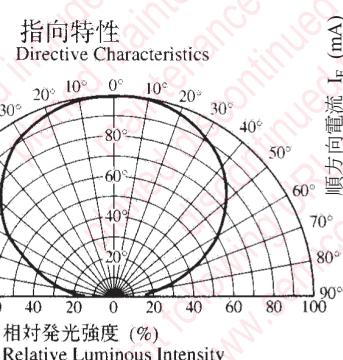
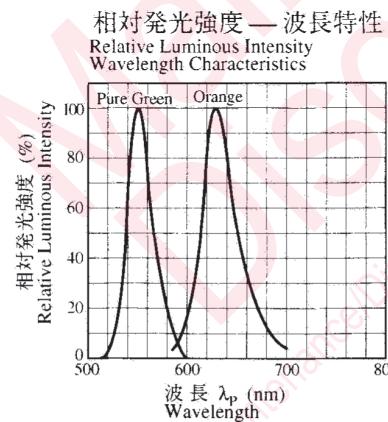
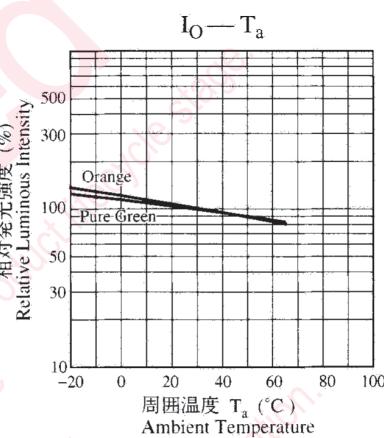
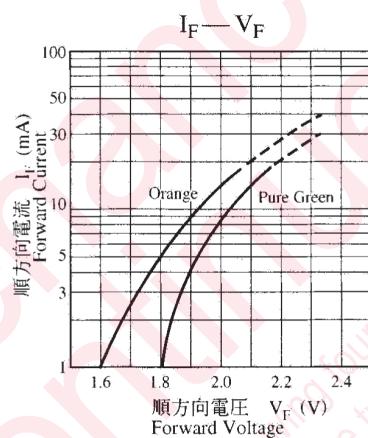
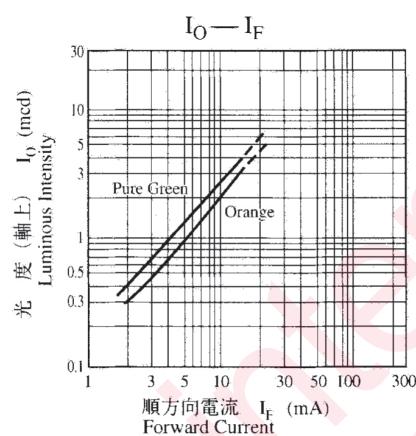
- Pure Green

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity	$I_O$		1.2	2.5		med
Forward current	$I_F$			10		mA
Forward voltage	$V_F$	$I_F = 10 \text{ mA}$		2.05	2.8	V
Peak emission wavelength	$\lambda_P$	$I_F = 10 \text{ mA}$		555		nm
Spectral half band width	$\Delta\lambda$	$I_F = 10 \text{ mA}$		25		nm
Reverse current	$I_R$	$V_R = 3 \text{ V}$			10	$\mu\text{A}$

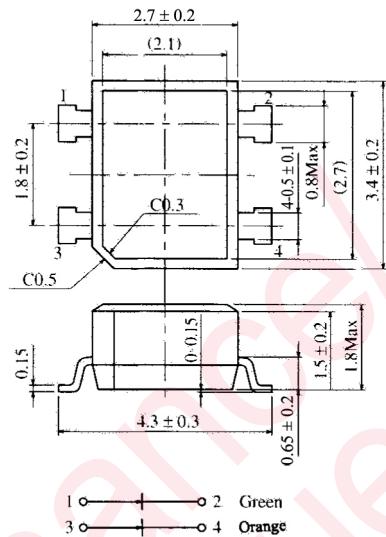
■ Electro-Optical Characteristics (Continued)  $T_a = 25^\circ\text{C}$ 

- Orange

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity	$I_O$		0.8	2.1		mcd
Forward current	$I_F$			10		mA
Forward voltage	$V_F$	$I_F = 10 \text{ mA}$		1.95	2.8	V
Peak emission wavelength	$\lambda_p$	$I_F = 10 \text{ mA}$		630		nm
Spectral half band width	$\Delta\lambda$	$I_F = 10 \text{ mA}$		40		nm
Reverse current	$I_R$	$V_R = 3 \text{ V}$			10	$\mu\text{A}$



## ■ Package (Unit: mm)



## • Pin name

- 1, 3: Anode
- 2, 4: Cathode

Maintenance/Discontinued includes following four Product lifecycle stage.  
planed maintenance type  
planed discontinued type  
discontinued type  
Please visit following URL about latest information.  
<http://www.semicon.panasonic.co.jp/en/>

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